

WATER SOLUBLE PROTECTIVE PASTE FOR MANUFACTURING PRINTED CIRCUIT BOARDS

Abstract

An improved water soluble protective paste and a method for protecting metal circuits and pads on the surface of an electronic board during the manufacturing steps. A densifier is added to the paste making it easier and more efficient the dispensing of the paste. After deposition the layer is dried until a solid protective film is obtained. An additional advantage obtained by the present invention is that the protective layer can be deposited also by means of an offset printing process, avoiding the use of the stencil and of the screening steps. Screening process is a labourious operation which requires very sophisticated equipment and a very high precision in the design of the stencil. Because of these requirements, screening is an expensive process. On the other hand offset printing is a very simple, cheap and reliable method. In addition, the film forming properties allow the material to create a protective film even with a thin deposited film.